PRELIMINARY

muRata
INNOVATOR IN ELECTRONICS

RFM products are now Murata products.

SF2364E

868.30 MHz

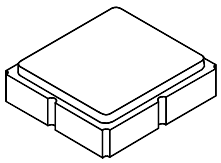
- ***AEC-Q200***
- ***Complies with Directive 2002/95/EC (RoHS)***

Characteristics:

Balance-to-balanced operation

Maximum Rating

Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-ground Terminal	0	V
Operating Temperature Range	-45 to +95	°C
Storage Temperature Range	-45 to +125	°C
Maximum Soldering Profile, 5 cycles/ 10 seconds maximum	265	°C



SM3030-8

Characteristic: Reference temperature 25 °C	Sym	Notes	Min	Typ	Max	Units
Center Frequency	F_C	1		868.30		MHz
Minimum Insertion Loss,	IL_{min}			2.9	4.2	dB
Passband (relative to IL_{min})						
868 to 868.78 MHz		1		1.0	3.0	dB
867.9 to 868.88 MHz				1.5	4.0	
Pass bandwidth (relative to IL_{min})	BW_3			1500		KHz
Attenuation, (relative to IL_{min}):						
10 to 700 MHz			50	55		
700 to 830 MHz			40	45		
830 to 850 MHz			35	40		
850 to 865.02 MHz		1	25	28		dB
871 to 874.5 MHz			15	20		
874.5 to 883 MHz			19	23		
883 to 900 MHz			30	35		
900 to 1000 MHz			40	45		
Impedance at FC $Z_{IN}=R_{IN}//C_{IN}$	117Ω // 3.7 pF					
$Z_{OUT}=R_{OUT}//C_{OUT}$	117Ω // 3.7 pF					

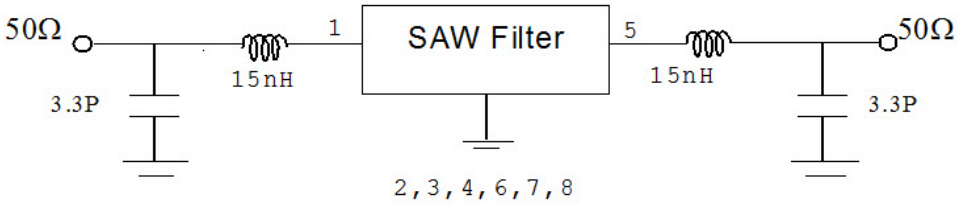
Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	5L, YWWS
Standard Reel Quantity Reel Size 7 inch	500 Pieces/Reel
Reel Size 13 inch	3000 Pieces/Reel

NOTES:

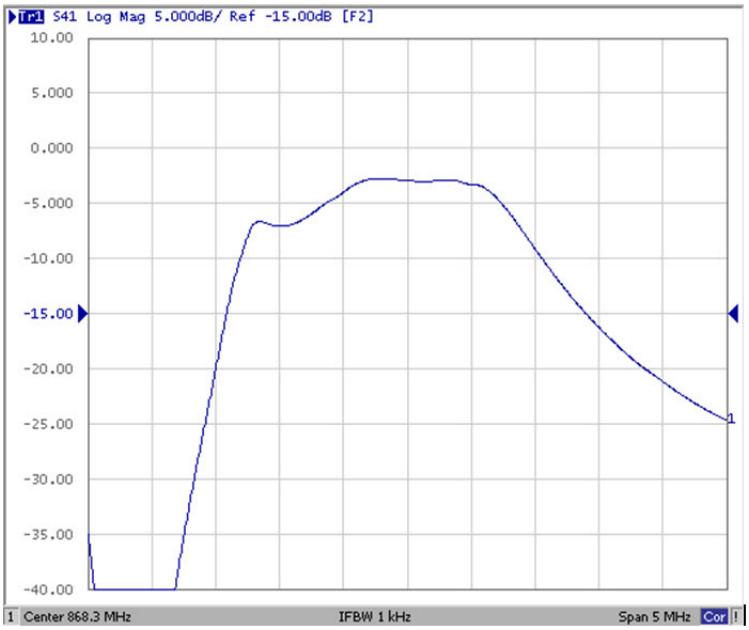
1. The standard definition is in JIS C 6703.
2. US and international patents may apply.
3. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.
4. Electrostatic Sensitive Device. Observe precautions for handling.

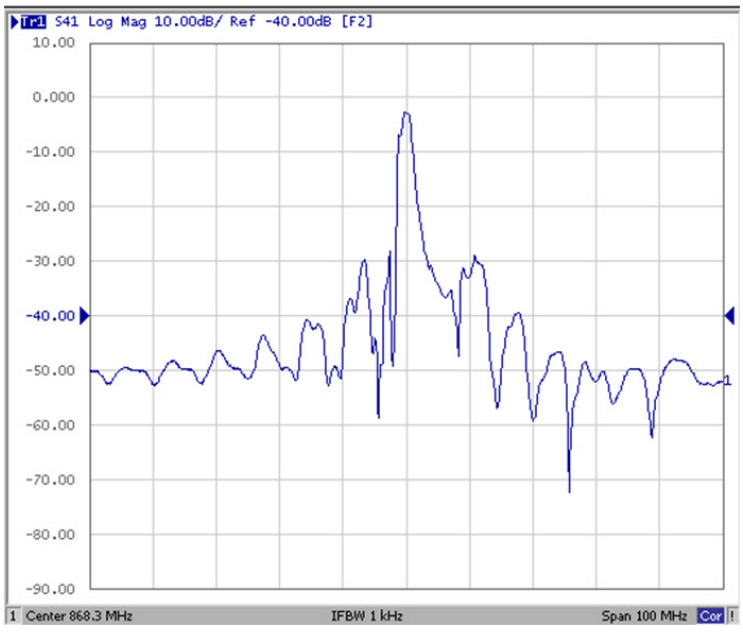
Measurement Circuit

Pin Description	
1	Input or Input Ground
2	Input Ground or Input
5	Output or Output Ground
6	Output Ground or Output
3, 4, 7, 8	Ground

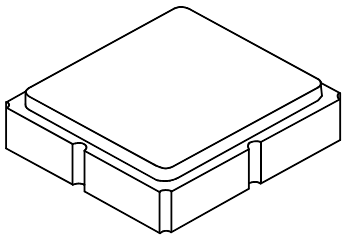


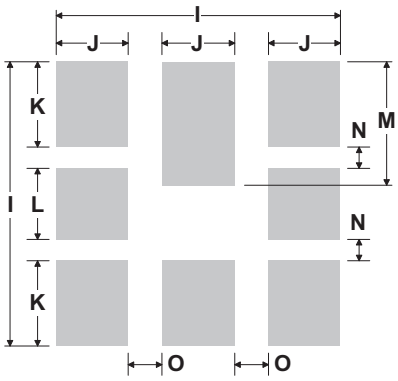
Frequency Characteristics





8-Terminal Ceramic Surface-Mount Case
3.0 X 3.0 mm Nominal Footprint





PCB Footprint Top View

Case and PCB Footprint Dimensions

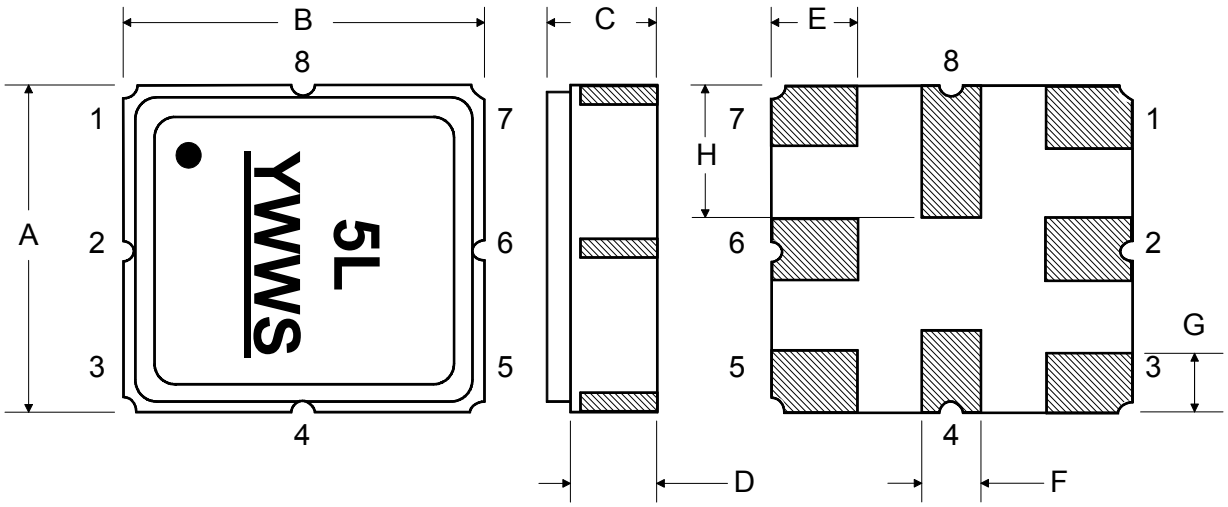
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	-	3.0	-	0.113	0.118	0.123
B	-	3.0	-	0.113	0.118	0.123
C	-	-	-	0.045	0.050	0.055
D	0.90	1.00	1.10	0.031	0.036	0.041
E	-	0.75	-	0.024	0.029	0.034
F	-	0.60	-	0.018	0.024	0.029
G	-	0.60	-	0.018	0.024	0.029
H	-	1.20	-	0.042	0.047	0.052
I	-	3.19	-	-	0.126	-
J	-	0.81	-	-	0.032	-
K	-	0.96	-	-	0.038	-
L	-	0.81	-	-	0.032	-
M	-	1.39	-	-	0.055	-
N	-	0.23	-	-	0.009	-
O	-	0.38	-	-	0.015	-

Case Materials

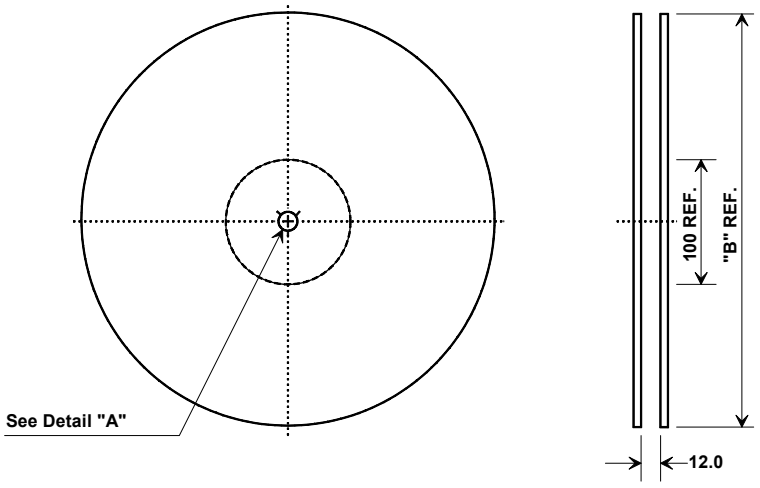
Materials	
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel
Lid Plating	2.0 to 3.0 µm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

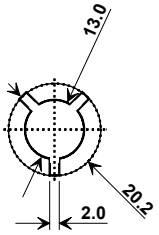
TOP VIEW

BOTTOM VIEW



Tape and Reel Specifications





"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm